

Abstract:

The present invention discloses a technology for a printed wiring board which uses a copper foil without roughening treatment. Therefore, An electrodeposited copper foil with carrier foil on which a resin layer for forming an insulating layer is formed, comprising a ~~which is sequentially~~ ~~constituted with~~ carrier foil, a bonding interface layer, an electrodeposited copper foil with smooth surfaces ~~surface~~ on both ~~side~~ sides and a resin layer is employed. The resin composition ~~constituting the resin layer~~ is composed of 20 to 80 parts by weight of an epoxy resin ~~which~~ ~~includes~~ and a curing agent, 20 to 80 parts by weight of a solvent soluble aromatic polyamide resin polymer and optionally a curing accelerator in a suitable amount ~~if required~~.